



SOD-123

SOD-123 贴片塑封稳压二极管
SOD-123 Plastic-Encapsulate Zener Diode

特征 Features

- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25 ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
存储温度 Storage temperature range	Ts	-65-+150	

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) f=1KHz

电特性 (TA = 25 除非另有规定)

Electrical Characteristics (Ratings at 25 ambient temperature unless otherwise specified.)

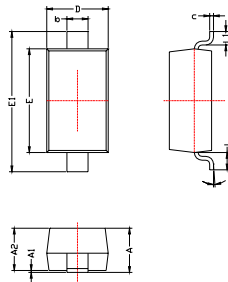
Device	Marking	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		Vz@Izt			Izt	Zzt @Izt	Zzk @Izk	Izk	IR	VR
		Nom(V)	Min(V)	Max(V)	mA			mA	uA	V
MM1Z 2V4	WX	2.4	2.2	2.6	5	100	600	1.0	120	1.0
MM1Z 2V7	W1	2.7	2.5	2.9	5	100	600	1.0	120	1.0
MM1Z 3V0	W2	3.0	2.8	3.2	5	95	600	1.0	50	1.0
MM1Z 3V3	W3	3.3	3.1	3.5	5	95	600	1.0	20	1.0
MM1Z 3V6	W4	3.6	3.4	3.8	5	90	600	1.0	10	1.0
MM1Z 3V9	W5	3.9	3.7	4.1	5	90	600	1.0	5	1.0
MM1Z 4V3	W6	4.3	4.0	4.6	5	90	600	1.0	5	1.0
MM1Z 4V7	W7	4.7	4.4	5.0	5	80	500	1.0	2	1.0
MM1Z 5V1	W8	5.1	4.8	5.4	5	60	480	1.0	2	1.5
MM1Z 5V6	W9	5.6	5.2	6.0	5	40	400	1.0	1	2.5
MM1Z 6V2	WA	6.2	5.8	6.6	5	50	150	1.0	1	3.0
MM1Z 6V8	WB	6.8	6.4	7.2	5	15	150	1.0	0.5	3.5
MM1Z 7V5	WC	7.5	7.0	7.9	5	15	50	1.0	0.5	4.0
MM1Z 8V2	WD	8.2	7.7	8.7	5	15	50	1.0	0.5	5.0
MM1Z 9V1	WE	9.1	8.5	9.6	5	15	50	1.0	0.5	6.0
MM1Z 10	WF	10	9.4	10.6	5	20	70	1.0	0.1	7.0
MM1Z 11	WG	11	10.4	11.6	5	20	70	1.0	0.1	8.0
MM1Z 12	WH	12	11.4	12.7	5	25	90	1.0	0.1	9.0
MM1Z 13	WI	13	12.4	14.1	5	30	110	1.0	0.1	10



MM1Z_C Series-II

Device	Marking	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		Vz@Izt			Izt	Zzt @Izt	Zzk @Izk	Izk	IR	VR
		Nom(V)	Min(V)	Max(V)	mA			mA	uA	V
MM1Z 15	WK	15	13.8	15.6	5	40	110	1.0	0.1	11
MM1Z 16	WL	16	15.3	17.1	5	40	170	1.0	0.1	12
MM1Z 18	WM	18	16.8	19.1	5	45	170	1.0	0.1	13
MM1Z 20	WN	20	18.8	21.2	5	50	220	1.0	0.1	15
MM1Z 22	WO	22	20.8	23.3	5	55	220	1.0	0.1	17
MM1Z 24	WP	24	22.8	25.6	5	60	220	1.0	0.1	19
MM1Z 27	WQ	27	25.1	28.9	5	70	220	1.0	0.1	21
MM1Z 30	WR	30	28.0	32.0	5	80	220	1.0	0.1	23
MM1Z 33	WS	33	31.0	35.0	5	80	220	1.0	0.1	25
MM1Z 36	WT	36	34.0	38.0	5	90	220	1.0	0.1	27
MM1Z 39	WU	39	37.0	41.0	2.5	130	350	0.5	2.0	30
MM1Z 43	WV	43	40.0	46.0	2.5	100	500	0.5	2.0	33
MM1Z 47	WW	47	44.0	50.0	2.5	100	600	0.5	2.0	36
MM1Z 51	WX	51	48.0	54.0	2.5	180	700	0.5	1.0	39
MM1Z 56	WY	56	52.0	60.0	2.5	180	700	0.5	1.0	43
MM1Z 62	WZ	62	58.0	66.0	2.5	200	1000	0.5	0.2	47
MM1Z 68	6F	68	64.0	72.0	2.5	250	1000	0.5	0.2	52
MM1Z 75	6H	75	70.0	79.0	2.5	300	1000	0.5	0.2	57
MM1Z 82	6J	82	77.0	87.0	2.5	300	1500	0.25	0.2	63
MM1Z 91	6K	91	85.0	96.0	1	700	2000	0.1	0.2	69
MM1Z 100	6M	100	94.0	106	1	700	5000	0.1	0.2	76

SOD-123 PACKAGE OUTLINE Plastic surface mounted package

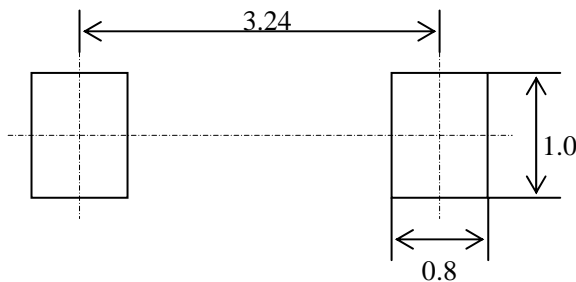


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24
脚宽: 0.55
焊盘宽: 1.00
脚长: 0.50
焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2: 未注公差为: ±0.05
- 3, 所有单位: mm